Assembly Site Transfer of Select CSP_BGA Products to STATS ChipPAC Korea

Qualification Results Summary
for CSP_BGA and BOM Change at STATS ChipPAC Korea

QUALIFICATION RESULT

TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	3 x 32	PASS
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC *JESD22-A118*	3 x 32	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	3 x 11	PASS
High Temperature Storage Life (HTSL)	JEDEC *JESD22-A103*	1 x 32	PASS

*Preconditioned per JEDEC/IPC J-STD-020